

WHAT IS CLAIMED IS:

1. A heat dissipating device with heat conductive posts comprising:
a substrate; a lower portion of the substrate being formed with a
5 plurality of via holes;

a plurality of heat conductive posts; the heat conductive posts being
axially embedded into the via holes of the substrate; and

a plurality of heat dissipating fins on one surface of the base.

2. The heat dissipating device with heat conductive posts as claimed in
10 claim 1, wherein in manufacturing process, one end of substrate is cut to
have a reduced narrow portion; the substrate enters into a through hole of
a shaping mold and the narrow portion protrudes from one opening of the
through hole and then enters into a clip to be clamped by the clip so that
surface of the heat conductive posts are tightly combined with inner walls
15 of the via holes; then, the substrate passes through the clip so be
compressed by the clip; thereby, the heat conductivity of the substrate is
changed by embedding with the heat conductive posts.

3. The heat dissipating device with heat conductive posts as claimed
in claim 2, wherein each heat conductive post has formed with a plurality
20 of ribs on an outer surface thereof.

4. The heat dissipating device with heat conductive posts as claimed in
claim 1, wherein the substrate is made of aluminum and the heat
conductive posts are made of copper.

5. The heat dissipating device with heat conductive posts as claimed in
25 claim 2, wherein the outer surface of each heat conductive post is coated

with tin glue; in the compressing process by the clip, the tin glue will permeate into the walls of the via holes of the substrate; the heat conductive posts and the substrate is combined tightly so as to have a preferred heat conductivity.